

# Product Carbon Footprint Dashboard

For Product: **pevwzhfyui**

**10.132 kg CO<sub>2</sub>e**

Total PCF per unit

**10.132**

Total Footprint (kg CO<sub>2</sub>e)

per 1.0 unit of pevwhfyui

**10.132**

Carbon Intensity (kg CO<sub>2</sub>e/unit)

based on 1.0 functional unit

**PCB**

Top Material Hotspot

3.0 kg CO<sub>2</sub>e from Printed Circuit Board

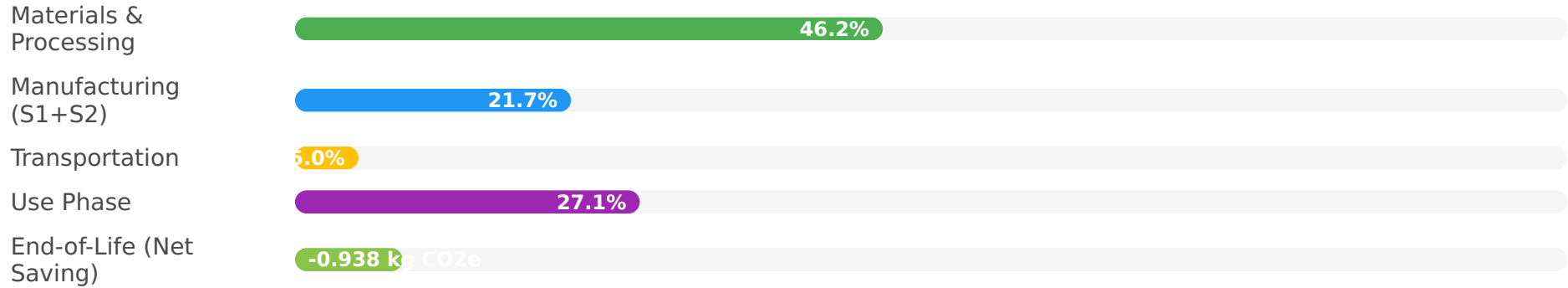
# Scope 3

Primary Emission Scope

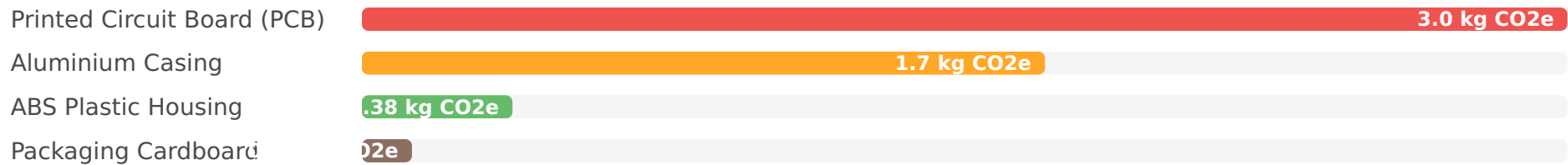
Accounts for over 70% of total PCF

# Emission Breakdown

## Lifecycle Stage Contributions



## Material Impact (kg CO2e)



## Key Highlights & Hotspots

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- **Material Acquisition & Processing** is the largest hotspot (46.2%), driven by high-impact components like PCBs and Aluminium.
- **Manufacturing (Scope 2)** contributes 21.7% of emissions, mainly due to the grid carbon intensity in China, despite 60% renewable energy use.
- The **Use Phase** accounts for a substantial 27.1% of the total footprint over the product's 5-year lifespan, emphasizing energy efficiency needs.

## Action Plan for Reduction

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- **Material Optimization:** Investigate and implement lower embedded carbon alternatives or reduce the quantity of high-impact materials.
- **Enhanced Renewable Energy Sourcing:** Increase the proportion of renewable energy beyond 60% at manufacturing sites, e.g., via Power Purchase Agreements.
- **Product Energy Efficiency:** Innovate to significantly reduce energy consumption during the product's active use phase.
- **Circular Economy Programs:** Strengthen existing take-back programs and explore wider material reuse and refurbishment initiatives.
- **Deep Supplier Engagement:** Collaborate closely with upstream suppliers to track, report, and reduce their emissions within Scope 3.

